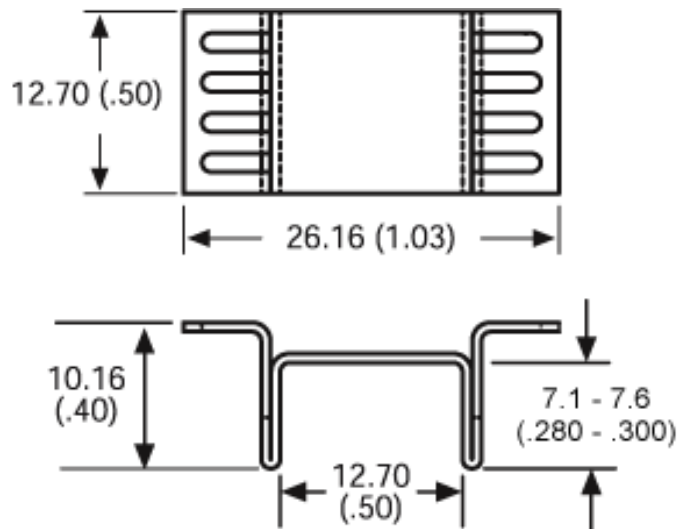


For use with Surface Mount packages

Part Number - 573300D00010G

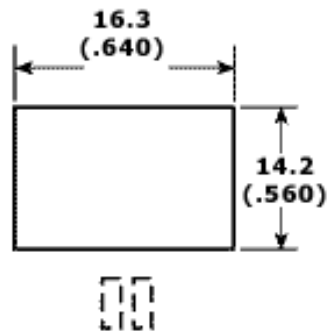
RoHS   
Compliant

## Mechanical Outline Drawing

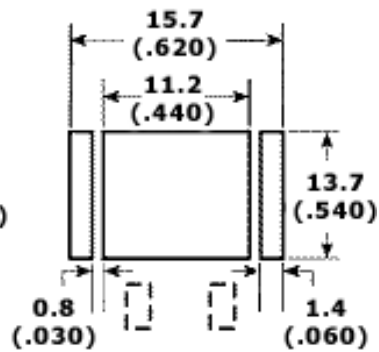


**Note:** The thickness of the drain pad is variable depending on the amount of heat generated by the SMT device, design, limitations and process. This is the exposed printed circuit.

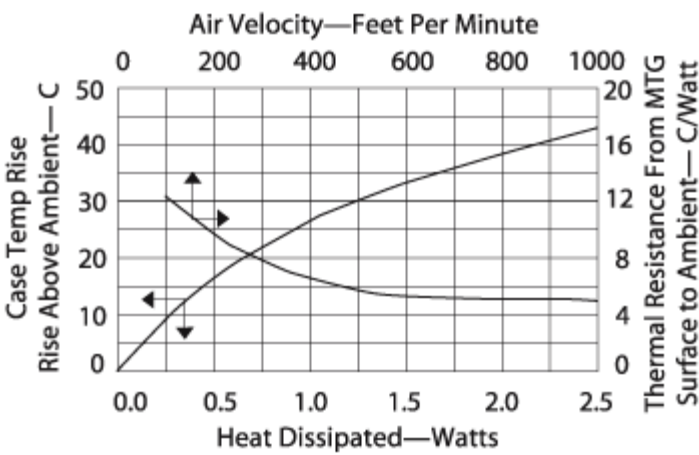
### Recommended Cu Heat Spreader Drain Pad



### Recommended Heat Sink Solder Mask Opening



Thermal Curves



Thermal Resistance	18.00
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Thermal resistance value is based on a 75°C rise in natural convection

Product Information

Part #	Description	Finish	Board Mounting
573300D00010G	Surface mount heat sink for D2 Pak (TO-263) package semiconductors	Matte Tin Plated	N/A
This non-electronic component is functionally unaffected by the normal soldering or reflow processes used for semiconductor circuits. The heat resistance time or heat resistance temperature is not applicable for the component.			